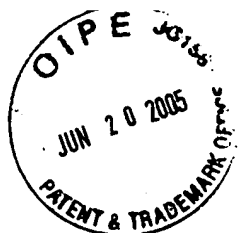


S/N 10/786,354



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Kie Y. Ahn et al.	Examiner:	Andy Huynh
Serial No.:	10/786,354	Group Art Unit:	2818
Filed:	February 25, 2004	Docket:	303.686US3
Title:	MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants request that the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p) be charged to Deposit Account No. 19-0743.

06/21/2005 ZJUHA1 00000023 190743 10786354
01 FC:1806 180.00 DA

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No :10/786,354

Filing Date: February 25, 2004

Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS

Page 2

Dkt: 303.686US3

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

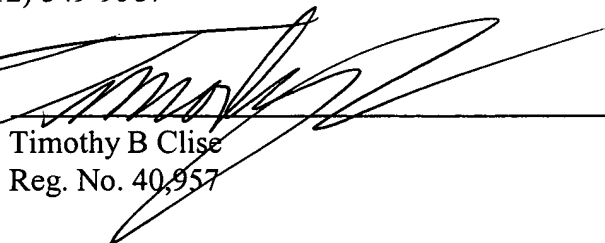
By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9587

Date

15 June '05

By

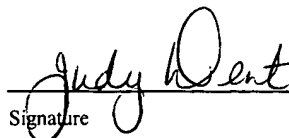

Timothy B Clise
Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 16th day of June, 2005.

Judy Dent

Name

Signature

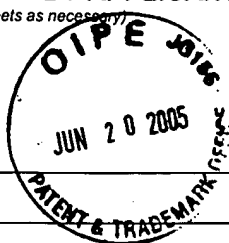


Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number	10/786,354
Filing Date	February 25, 2004
First Named Inventor	Ahn, Kie
Group Art Unit	2818
Examiner Name	Huynh, Andy

Sheet 1 of 1

Attorney Docket No: 303.686US3

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
	US-5,953,626	09/14/1999	Hause, F. N., et al.	06/05/1996
	US-6,342,722	01/29/2002	Armacost, M., et al.	08/05/1999
	US-6,413,827	07/02/2002	Farrar, Paul A.	02/14/2000
	US-6,633,074	10/14/2003	Ahn, K. Y.	06/03/1999

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional) ² Applicant is to place a check mark here if English language Translation is attached

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

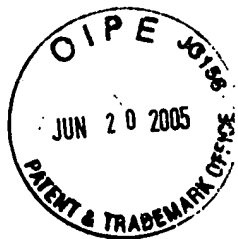
Applicant: Kie Y. Ahn et al.

Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS

Docket No.: 303.686US3

Filed: February 25, 2004

Examiner: Andy Huynh



Serial No.: 10/786,354

Due Date: N/A

Group Art Unit: 2818

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

☒ A return postcard.

☒ A Supplemental Information Disclosure Statement (2 pgs.), and Form 1449 (1 pg.) Documents NOT enclosed.

☐ A check in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

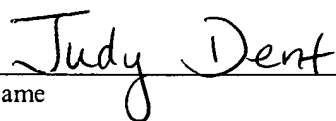
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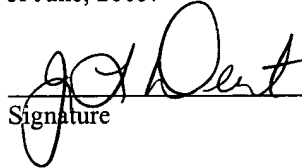
By: 

Atty: Timothy B. Clise

Reg. No. 40,957

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 16th day of June, 2005.


Name


Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)



Receipt is hereby acknowledged for the following in the United States Patent and Trademark Office:

In re Patent Application of: Kie Y. Ahn et al.

Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS
AND AIR GAPS

Serial No.: 10/786,354

Filing Date: February 25, 2004

CONTENTS: An Supplemental Information Disclosure Statement (2 pgs.),
Form 1449 (1 pg.), Return Postcard and Transmittal Sheet.

Mailed: June 16, 2005
TBC/jld

Docket No.: 303.686US3
Due Date: N/A